

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filing system in accordance with § 1.6(a)(4).

Dated: June 2, 2009  
Electronic Signature for James E. Armstrong, IV: /James E. Armstrong, IV/

Docket No.: 80428(302761)  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Kunihiro Kakihara et al.

Application No.: 10/561,966

Confirmation No.: 1627

Filed: December 22, 2005

Art Unit: 1792

For: RESIN PLATING METHOD WITH ADDED  
HEAT-TREATING PROCESS

Examiner: N. T. Leong

**AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir/Madam:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated February 2, 2009, please amend the above-identified U.S. patent application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks** begin on page 5 of this paper.